# **INDEX TO VOLUME 5**

### **Author Index**

BAKER, L. Paper on 'Applications of sensors to product

inspection', 89-94. BLACKBURN, K. See RENNIE, D., MORRIS, W. and BLACKBURN, K.

CAPLEN, R. Paper on 'A history of the Institute of Quality Assurance', 49-65.

CARTER, A.D.S. Paper on 'The interaction between some simple load and strength distributions', 3-8.

DURRANT, N.F. Paper on 'The sign test', 9-11.

GOLDSWORTHY, B. Paper on 'The challenge of product recall', 21-26.

ISHIKAWA, K. Paper on 'Quality control in Japan',

JENSEN, F. and PETERSEN, N.E. Paper on 'Burn-in models for non-repairable and repairable equipment based upon bi-modal component lifetimes, 103-7.

JURAN, J.M. Paper on 'Japanese and Western quality: a contrast', 12-17.

LOXHAM, J. Paper on 'The historical development and future potential of quality assurance as a national strategy', 31-36.

McKEOWN, P.A. Paper on 'Quality through technology', 37-47.

McROBB, R.M. Paper on 'The next sixty years', 66-68. MATFIELD, R. Paper on 'Reliability transfer', 82-84, 88. MIDDLETON, V. Paper on 'Applications of minicomputers to shop-floor inspection', 95-98.

MORRIS, W. See RENNIE, D., MORRIS, W. and BLACKBURN, K.

MORRISON, J. Paper on 'The role of statistician in a test environment', 108-12.

O'CONNOR, P.D.T. Paper on 'Microelectronic systems reliability prediction', 113-16, 121.

OWEN, M.H. Paper on 'Statistics, economics, and the consumer', 75-81.

PETERSEN, N.E. See JENSEN, F. and PETERSEN, N.E.

RAE, J.C. Paper on 'Establishing a cost-effective system of total quality, 85-88.

RENNIE, D., MORRIS, W. and BLACKBURN, K. Paper on 'Quality assurance: the modern concept of third-party inspection', 71-74.

TATHAM, W. Paper on 'BS 9000 and other systems for the procurement of electronic components of assessed quality', 122-27. TURPIN, M.P. See WARREN, J.H. and TURPIN, M.P.

WARREN, J.H. and TURPIN, M.P. Paper on 'Design and development of reliable software', 117-21.

## Subject Index

Acceptable quality levels (AQLs), 15. Analysis of variance, 111.

Arrhenius functions, 115.

Bayes theorum, 111.

Bi-modal distribution of component lifetimes, 103. Bond failure, 114.

BS 9000 system for procurement of electronic components, 122. present state of, 125.

Burn-in models, 103.

of repairable equipment, 104.

Burn-in procedures, 103, 104.

CECC system for electronic components, 125.

Certificate of Competence, 63, 64.

Change, resistance to, 37.

Checkweighing, 75, 76.

developments in, 80.

Colour television sets, Japanese and Western quality

compared, 12.

Communications, future developments in, 67.

Competitiveness, need to improve, 37.

Component lifetimes, bi-modal distribution of, 103. Component quality, Japanese and Western compared, 14, 15.

Computers, mini-computers for inspection, 95.

Concrete, epoxy, for high-precision machine-tool structures, 46.

Conformance testing of electronic components, 124. Cost-effective quality system, 85. Cranfield Institute of Technology, 45.

Crosfield Electronics Ltd., electronic products for printing industry, 42-44.

Cylinder bores, inspection of, 91.

Defects, prevention of, 86.

Design and quality assurance, 85.

Designers, training of, Japanese and Western compared, 14.

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BAKER, L. Paper on 'Applications of sensors to product

inspection', 89-94. BLACKBURN, K. See RENNIE, D., MORRIS, W. and BLACKBURN, K.

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DURRANT, N.F. Paper on 'The sign test', 9-11.

GOLDSWORTHY, B. Paper on 'The challenge of product recall', 21-26.

ISHIKAWA, K. Paper on 'Quality control in Japan',

JENSEN, F. and PETERSEN, N.E. Paper on 'Burn-in models for non-repairable and repairable equipment based upon bi-modal component lifetimes, 103-7.

JURAN, J.M. Paper on 'Japanese and Western quality: a contrast', 12-17.

LOXHAM, J. Paper on 'The historical development and future potential of quality assurance as a national strategy', 31-36.

McKEOWN, P.A. Paper on 'Quality through technology', 37-47.

McROBB, R.M. Paper on 'The next sixty years', 66-68. MATFIELD, R. Paper on 'Reliability transfer', 82-84, 88. MIDDLETON, V. Paper on 'Applications of minicomputers to shop-floor inspection', 95-98.

MORRIS, W. See RENNIE, D., MORRIS, W. and BLACKBURN, K.

MORRISON, J. Paper on 'The role of statistician in a test environment', 108-12.

O'CONNOR, P.D.T. Paper on 'Microelectronic systems reliability prediction', 113-16, 121.

OWEN, M.H. Paper on 'Statistics, economics, and the consumer', 75-81.

PETERSEN, N.E. See JENSEN, F. and PETERSEN, N.E.

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## Subject Index

Acceptable quality levels (AQLs), 15. Analysis of variance, 111.

Arrhenius functions, 115.

Bayes theorum, 111.

Bi-modal distribution of component lifetimes, 103. Bond failure, 114.

BS 9000 system for procurement of electronic components, 122. present state of, 125.

Burn-in models, 103.

of repairable equipment, 104.

Burn-in procedures, 103, 104.

CECC system for electronic components, 125.

Certificate of Competence, 63, 64.

Change, resistance to, 37.

Checkweighing, 75, 76.

developments in, 80.

Colour television sets, Japanese and Western quality

compared, 12.

Communications, future developments in, 67.

Competitiveness, need to improve, 37.

Component lifetimes, bi-modal distribution of, 103. Component quality, Japanese and Western compared, 14, 15.

Computers, mini-computers for inspection, 95.

Concrete, epoxy, for high-precision machine-tool structures, 46.

Conformance testing of electronic components, 124. Cost-effective quality system, 85. Cranfield Institute of Technology, 45.

Crosfield Electronics Ltd., electronic products for printing industry, 42-44.

Cylinder bores, inspection of, 91.

Defects, prevention of, 86.

Design and quality assurance, 85.

Designers, training of, Japanese and Western compared, 14.

membership, 62. Distortion graticule, 91. Drawing-office practice, 34. miscellaneous activities, 61. regions, 62, 64. Economic decline as national problem, 37. Institution of Engineering Inspection 1922-28, 52. EEC directives on prepacked products, 79. Electronic components 1929-32, 53. BS 9000 system, 122. 1932-35, 53. 1936-39, 54. 1939-46, 54. capability approval, 124. CECC system for, 125 conformance testing of, 124. 1947-53, 55. IEC(QA) system for, 125. of assessed quality, 122. 1954-58, 56. 1958-64, 56. qualification approval, 123. 1965-69, 57. UK national organization for, 126. 1969-72, 58. Electronic devices, failure rate prediction, 113. association with Institution of Production Engineers, Electronics industry, explosion in, 66. Employee relations, Japanese and Western compared, 16. Engineering and quality assurance, 86. branches, 53, 54, 55, 56, 57. change of name, 58, 60. Epoxy concrete for high-precision machine-tool struc-Council reorganization, 57. tures, 46. examinations, 56, 59. finances, 52, 53, 55, 56, 57, 59. formation of, 52. Excessive variation, cause of, 9. Failure Golden Jubilee, 58. headquarters, 55, 56, 58. and environmental conditions, 8. initial progress, 52. early-life, 8. in micro-electronic systems, 113. journal, 59. List of Office s, 65. membership, 53, 55, 56, 58, 59. Failure model, 104. Failure rate organization, 56. constant, 8 organizer-secretary, 54. professional status, 58. expression for, 4. prediction for micro-electronic systems, 113. quality control, 55, 56. zero, 8. registration of technicians and technician engineers, 59 second world war and aftermath, 54. Glare measurement, 91. technical proceedings, 53. Graticules for product inspection sensors, 89. Interchangeability, development and use of systems of, 33 Interferometry, development of, 32. Hermeticity failure, 114. Iron Ulna (standard yard), 31. Hypothesis testing, 110. IEC(QA) system for electronic components, 125. quality control in, 18. training in, 19. Innovation Japanese and Western differences in quality control, characteristics of successful companies, 41. examples of British, 41-45. 12, 18. Japanese Industrial Standards (JIS) certification mark, finance for, 45. how it happens, 40. need for, 38. John Loxham Lecture, 37. opportunities for, 45. technological, assistance in, 45. Kearney and Trecker Marwin Ltd., machining centres, who causes it to happen? 40. Inspection and production, 35. Legislation data feedback, 15. future developments in, 67. for stress concentration, 92. prepacked products, 75. integrated systems, 98. Length standards, improvement in measurement of, 33. mini-computer applications, 95. Lifetime distributions of cylinder bores, 91. bi-modal, 103. of narrow strip materials, 91. for non-repairable equipment, 103. Limits and fits, 34. of television lenses, 89. sensor applications, 89. Lloyd's Register of Shipping, 74. third-party, 71. Institute of Quality Assurance, 60-65. Load and strength distributions, 3. 'Loading roughness', 115. 1972-75, 60. 1975-79, 63. Machine tools branches, 62, 64. epoxy concrete, 46. Certificate of Competence, 63, 64. improvement in precision of, 33. Machining centres, NC/CNC four-axis horizontal, 42. choice of name, 60. Diamond Jubilee, 65. Manufacturing and quality assurance, 86. entrance examinations, 62, 64. Manufacturing accountability and quality assurance, 86. finances, 62, 64. Measurement future developments, 66. achieving accuracy in, 35. direct, 35. headquarters, 60, 63. headquarters activities, 63. Measuring equipment future developments of, 36. journal, 62.

international recognition of, 35.

List of Officers, 65.

justifying the use of, 35. Metre, development of, 32. Microelectronic systems device complexity, 113. device level considerations, 115. failure causes in, 113. failure rate prediction, 113. general device-level model, 115. proposed failure rate model device level, 115. system level, 115. reliability prediction in, 113. MIL HBK 217C formula, 113. Mini-computers for inspection, 95. Modular transfer function (MTF), 89. Modulation transfer function (MTF), 90. Multiple regression analysis, 110. Multiplication rule, 9.

Narrow strip materials, inspection of, 91. National Council for Quality and Reliability, 60. National strategy for quality assurance, 36. Null hypothesis, 9.

Organization for quality, Japanese and Western com-

pared, 16. Prepacked products, legislation, 75. Printing industry, electronic products, 42-44. Probability, calculation of, 9 Probability distributions, 110. Probability levels in sign test, 10. Process control, Japanese and Western compared, 16. Process design Japanese and Western compared, 14, 15. need for, 40. Product innovation, 38. Product liability, 21, 85.

bibliography, 24. future developments in, 67. Product life cycle, 40. Product performance feedback, 15.

Product recall, 21. after the event, 22. definition of, 21. manufacturer's responsibility, 21. setting up recall procedure, 22. types of recall, 22.

Production and inspection, 35. Productivity, need to improve, 37-38. Promotion activities, 19.

Quality, function of, 86. Quality assurance and design, 85. and engineering, 86. and manufacturing, 86. and manufacturing accountability, 86. and reliability, 83. examples from the past, 31. function of, 41. future developments, 66. future potential as national strategy, 31. historical development, 31. national strategy for, 36. third-party inspectorates, 71. Quality control in IEI records, 55, 56. in Japan, 18.

Quality performance criteria, 15. Quality plan, preparation of, 72.

Japanese and Western compared, 14.

Quantity control, checkweighing, 76.

Quality planning

joint, 15.

Random variation, 11. Reliability and failure rate, 4. and quality assurance, 83. expression for, 6. load and strength distribution study, 3. of software. See Software. organizing for, 83. selection of optimal test plan, 108. testing for, 108. Reliability analysis, 82. Reliability prediction in microelectronic systems, 113. Reliability transfer, concept of, 82. Rolled-steel products, inspection procedure, 72. Sensors for product inspection, 89. Sequential analysis, 110. Shewhart chart, 76. Sign test, 9. applications, 9-11. probability levels in, 10. S-N curve, 110. Software, design principles of structure programming, 119. Software development systems, 121. Software preparation and production, deficiencies in standards for, 117. Software reliability, design and development aspects, 117. Software system structure and architecture, 117.

Standard yard, 31. Standards, length, improvement in measurement of, 33. Statistical methods, 9, 19 in test environment, 108. Statistician, role in test environment, 108. Statistics, economics and the consumer, 75. Stepwise regression, 111. Stress concentration, inspection for, 92. Structured programming, 117. design principles, 119 development tools and techniques, 120. implementation of, 120.

program validation, 120.

Technical Inspection Association, 35, 49-52. Television lenses, inspection of, 89. Television sets, colour, Japanese and Western quality compared, 12. Third-party inspectorates, 71.
TI Churchill, NC/CNC turning machines, 42. Tolerances and interchangeability, 34-35. Torpedos, assembly of flanged components, 33-34. Total quality approach, 85. 'Trade-off' characteristics, 110. Trading Standards Officer, 75, 80. Training in Japan, 19. Japanese and Western compared, 17. of designers, Japanese and Western compared, 14. Transmission measurement, 91. Transverse chromatic aberration, measurement of, 91.

Variation analysis, 9. Voltage-controlled oscillator (VCO), 46.

Turning machines, NC/CNC, 42.

Turbo-alternator sets, inspection procedure, 73.

Wafer fabrication processes, 113. Weibull analysis, 110. Weibull distribution, 8, 108. Weights and Measures Act, 1963, 75, 76.

American, 32. standard, 31.

